

## ABSTRACT

A method for singulating a substrate containing semiconductor components is performed using a nest for holding the substrate, a prestage alignment base for aligning the substrate during a prestage alignment step, and a vacuum cutting base for holding the nest and the substrate during a cutting step. The prestage alignment base includes locator pins configured to engage locator openings on the substrate to align the substrate on the nest. As the cutting base does not include the locator pins, the cutting step can be performed without saw scrap collecting on the locator pins. A system for performing the method includes the nest and the prestage alignment base having the locator pins configured to engage the locator openings on the substrate. The system also includes the sawing base which includes pedestals with vacuum conduits for holding the substrate stationary on the nest for sawing. The system also includes the saws, and a vacuum source in flow communication with the vacuum conduit and pedestals on the sawing base.

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